

EAST - [10652790.wsp:1]

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 (34202) lead near frame  
 (3595) (lead near frame) and protrud\$3  
 (773) ((lead near frame) and protrud\$3) and inner near lead\$1  
 (264) (((lead near frame) and protrud\$3) and inner near lead\$1) and ((inner near lead\$1) with pr  
 (385) quad adj flat adj non-leaded or 'QFN'  
 (163) quad adj flat adj non-leaded  
 (1) ("6075284").PN.  
 (21) (((lead near frame) and protrud\$3) and inner near lead\$1) and ((inner near lead\$1) with pr  
 (0) quad adj flat adj non-leaded and insulat\$2 near tape  
 (264) (((lead near frame) and protrud\$3) and inner near lead\$1) and ((inner near lead\$1) with pr  
 (5530) (((lead near frame)) and inner near lead\$1)  
 (261) (((lead near frame)) and inner near lead\$1) and insulat\$2 near tape  
 (261) (((lead near frame)) and inner near lead\$1) and insulat\$2 near tape  
 (1) ("5952714").PN.  
 (1) ("6297543").PN.  
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 (((lead near frame) and protrud\$3) and inner near lead\$1) and ((inner near lead\$1) with protrud\$3)

BR IS MH Text H

	U	I	Document ID	Issue Date	Pages	Title	Current OR	Current XRef
1	<input type="checkbox"/>	<input type="checkbox"/>	US 20040155323 A1	20040812	70	Semiconductor device	257/676	
2	<input type="checkbox"/>	<input type="checkbox"/>	US 20040104458 A1	20040603	11	Semiconductor device and method for manufacturing same	257/669	257/680; 257/704;
3	<input type="checkbox"/>	<input type="checkbox"/>	US 20040099933 A1	20040527	22	Resin-sealed-type semiconductor device, and production process for producing such	257/675	257/676; 257/707;
4	<input type="checkbox"/>	<input type="checkbox"/>	US 20040097082 A1	20040520	53	Semiconductor device having radiation structure	438/689	257/E23.084; 257/E23.092;
5	<input type="checkbox"/>	<input type="checkbox"/>	US 20040097016 A1	20040520	25	Semiconductor package and method of making leadframe having lead locks to	438/124	257/676; 257/E23.039;
6	<input type="checkbox"/>	<input type="checkbox"/>	US 20040089942 A1	20040513	53	Semiconductor device having radiation structure	257/718	257/E23.084; 257/E23.092;
7	<input type="checkbox"/>	<input type="checkbox"/>	US 20040089941 A1	20040513	53	Semiconductor device having radiation structure	257/718	257/719; 257/720;
8	<input type="checkbox"/>	<input type="checkbox"/>	US 20040089940 A1	20040513	53	Semiconductor device having radiation structure	257/718	257/719; 257/E23.084;
9	<input type="checkbox"/>	<input type="checkbox"/>	US 20040089925 A1	20040513	53	Semiconductor device having radiation structure	257/676	257/E23.084; 257/E23.092;
10	<input type="checkbox"/>	<input type="checkbox"/>	US 20040089923 A1	20040513	40	Semiconductor device and its manufacturing method	257/668	257/E23.038
11	<input type="checkbox"/>	<input type="checkbox"/>	US 20040089921 A1	20040513	15	Lead frame and method of producing the same, and resin-encapsulated	257/666	